

APPENDIX D – MODIFICATION LIST

1. On the Mainframe Assembly.

Before



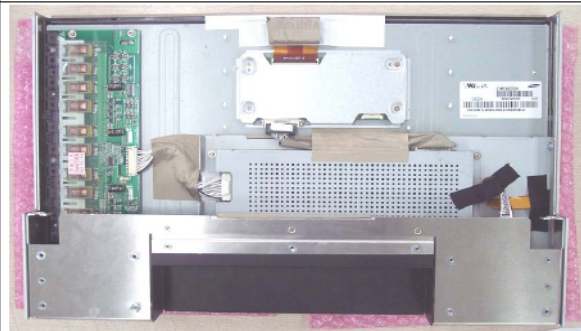
After



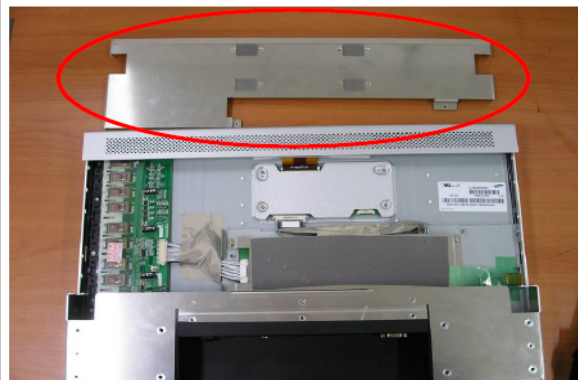
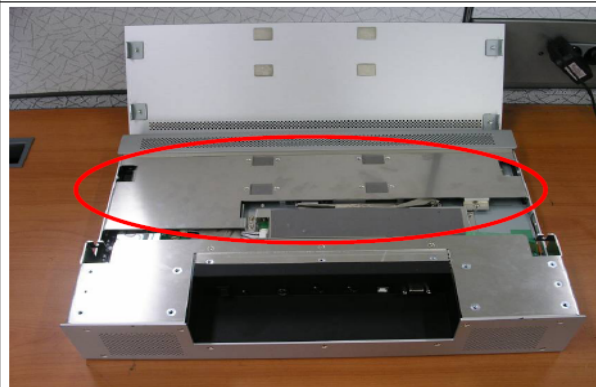
1) Backside of mainframe is split to two pieces.

2. On the backside of mainframe and bracket.

Before



After





1) Add the bracket for attaching the backside of mainframe

3. On the bracket for attaching the backside of mainframe

Before	After
There is no bracket before 2 piece of mainframe model.	
1) Add the EMI gasket for increasing conductance between mainframes and bracket.	

4. EMI Gasket on top of LCD panel

Before	After
	
1) Cut off the EMI Gasket on top of LCD panel for attaching Thermal pad.	

5. On the side-plate

Before



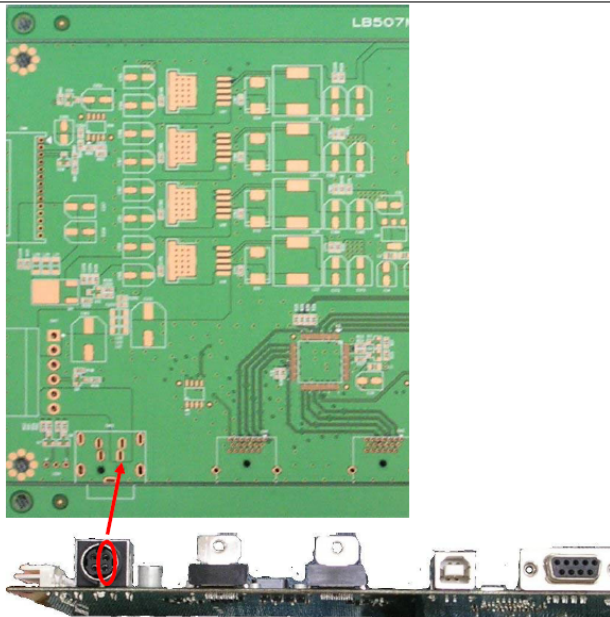
After



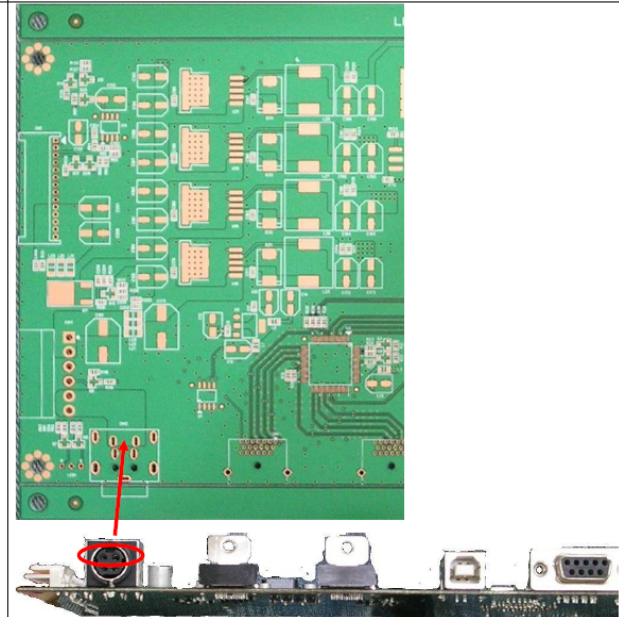
1) Glue point of double stick EMI Tape is changed since the assembly method of the side-plate is changed.

6. DC power connector

Before

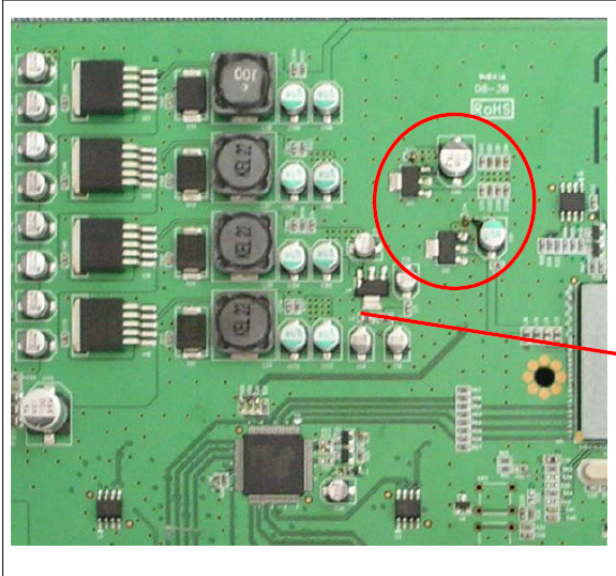
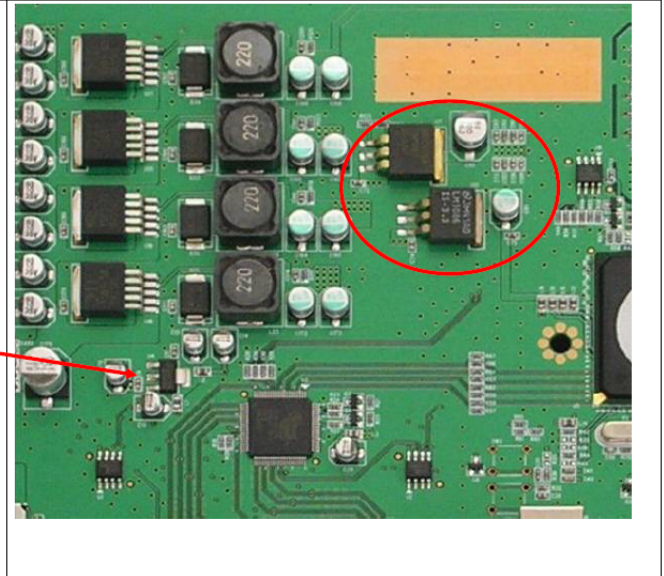


After



- 1) DC power connector pin assign is changed through changing the pin assign of AC/DC adaptor jack.
- 2) AC/DC adaptor is changed to FSP group inc. FSP135-AAAN1 from Lishin 0227B24130.

7. Power source

Before	After
	
<p>1) LDO is changed for DC power stabilization.(U11 – from LM1117MPX-2.5 to LM1085ISX-ADJ, U12 – from LM1117MPX-3.3 to LM1086ISX-5.0)</p> <p>2) LDO position is changed for DC power stabilization.(U4)</p>	

APPENDIX E – BLOCK DIAGRAM

APPENDIX F – USER’S MANUAL

APPENDIX G – SCHEMATIC DIAGRAM
